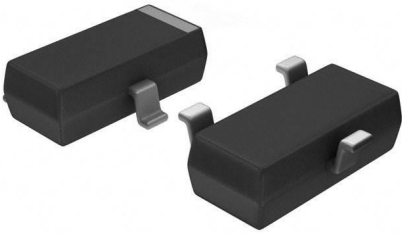


2SD13280TL Datasheet

www.digi-electronics.com



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	2SD13280TL-DG
Manufacturer	Panasonic Electronic Components
Manufacturer Product Number	2SD13280TL
Description	TRANS NPN 20V 0.5A MINI3
Detailed Description	Bipolar (BJT) Transistor NPN 20 V 500 mA 200MHz 200 mW Surface Mount Mini3-G1



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:

2SD13280TL

Series:

-

Transistor Type:

NPN

Voltage - Collector Emitter Breakdown (Max):

20 V

Current - Collector Cutoff (Max):

100nA (ICBO)

Power - Max:

200 mW

Operating Temperature:

150°C (TJ)

Package / Case:

TO-236-3, SC-59, SOT-23-3

Base Product Number:

2SD1328

Manufacturer:

Panasonic Electronic Components

Product Status:

Obsolete

Current - Collector (Ic) (Max):

500 mA

Vce Saturation (Max) @ Ib, Ic:

400mV @ 20mA, 500mA

DC Current Gain (hFE) (Min) @ Ic, Vce:

400 @ 500mA, 2V

Frequency - Transition:

200MHz

Mounting Type:

Surface Mount

Supplier Device Package:

Mini3-G1

Environmental & Export classification

Moisture Sensitivity Level (MSL):

1 (Unlimited)

HTSUS:

8541.21.0075

ECCN:

EAR99

2SD1328

Silicon NPN epitaxial planar type

For low-voltage output amplification

For muting

For DC-DC converter

■ Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Low ON resistance R_{on}
- High forward current transfer ratio h_{FE}

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	25	V
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Emitter-base voltage (Collector open)	V_{EBO}	12	V
Collector current	I_C	0.5	A
Peak collector current	I_{CP}	1	A
Collector power dissipation	P_C	200	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10 \mu\text{A}, I_E = 0$	25			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	20			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$	12			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 25 \text{ V}, I_E = 0$			100	nA
Forward current transfer ratio *1,2	h_{FE}	$V_{CE} = 2 \text{ V}, I_C = 0.5 \text{ A}$	200		800	—
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = 0.5 \text{ A}, I_B = 20 \text{ mA}$		0.13	0.40	V
Base-emitter saturation voltage *1	$V_{BE(sat)}$	$I_C = 0.5 \text{ A}, I_B = 50 \text{ mA}$			1.2	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C_{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		10		pF
ON resistance *3	R_{ON}			1.0		Ω

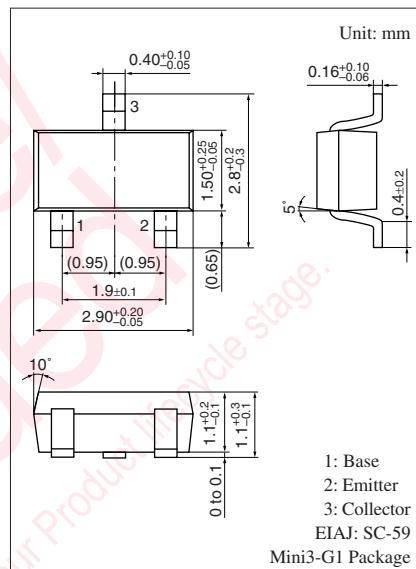
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement

*2: Rank classification

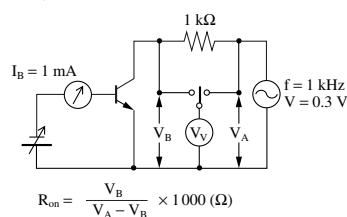
Rank	R	S	T	No-rank
h_{FE}	200 to 350	300 to 500	400 to 800	200 to 800
Marking symbol	1DR	1DS	1DT	1D

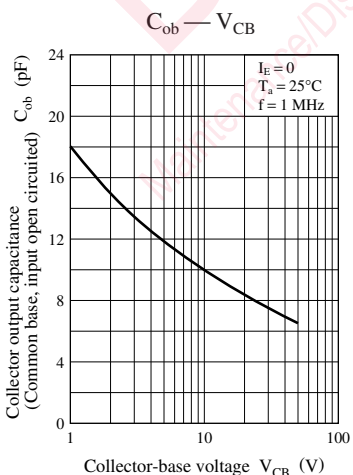
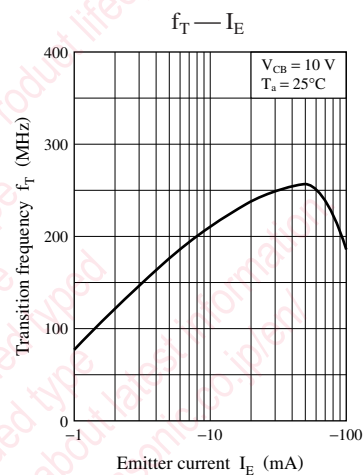
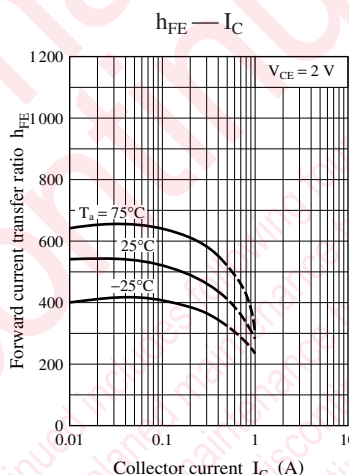
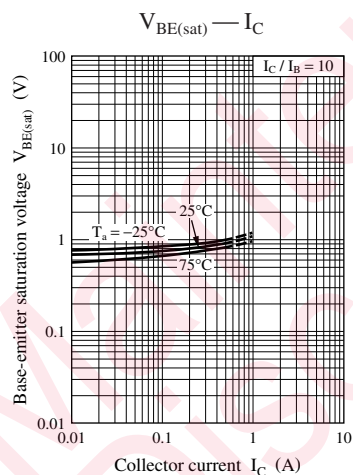
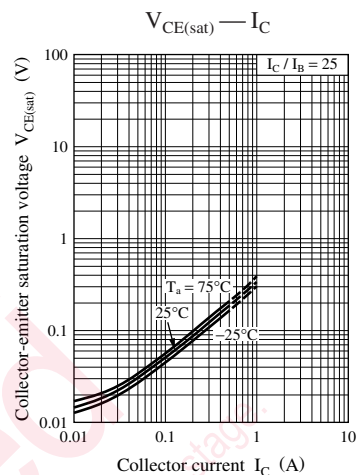
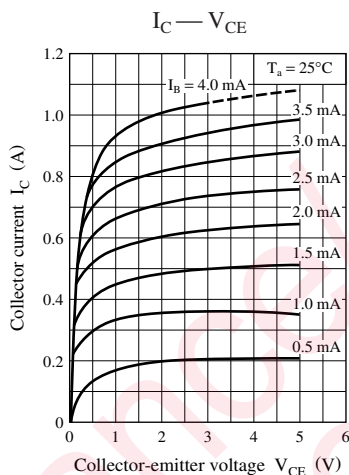
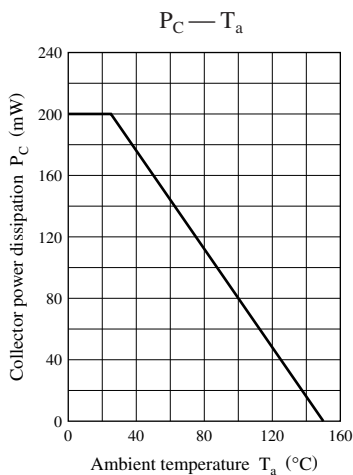
Product of no-rank is not classified and have no marking symbol for rank.



Marking Symbol: 1D

*3: R_{on} Measurement circuit





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